IEC 60191-2

Edition 1.0 2018-04

INTERNATIONAL STANDARD

AMENDMENT 20

The sheets contained in this amendment are to be inserted in IEC 60191-2

Mechanical standardization of semiconductor devices – Part 2: Dimensions



IEC 60191-2:1966/AMD20:2018-04(en)



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Replace the existing title page with the new title page.

Remove the existing page 60191 IEC I containing the preface and insert in its place the new page 60191 IEC I containing the preface to Amendment 20 (2018).

Chapter I:

Add the following new sheets:

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MECHANICAL STANDARDIZATION OF SEMICONDUCTOR DEVICES –

Part 2: Dimensions

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Amendment 20 (2018) to IEC 60191-2 (1966)

MECHANICAL STANDARDIZATION OF SEMICONDUCTOR DEVICES –

Part 2: Dimensions

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PREFACE TO AMENDMENT 20 (2018)

This amendment has been prepared by subcommittee 47D: Semiconductor Packaging, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47D/900/FDIS	47D/906/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.